

Appendix-3

TRIPARTITE AGREEMENT FOR THE SUPPLY OF DESFIRE CONTEACTLESS

THIS agreement is made at NEW DELHI on this -----day of -----2011

BETWEEN

THE Delhi Metro Rail Corporation Ltd, which is a Joint venture of Govt of India and Govt of Delhi, herein after called Delhi Metro, through its Mr----- on the ONE PART

AND

M/S -----, a company -----herein after called "OEM Chip Manufacturer"

AND

M/S-----HAVING ITS Registered Office at ----- through its Director-----hereinafter called the " Card Vendor"

HEREIN after called the TRIPARTITE AGREEMENT for the manufacture and supply of the 4 KB DESfire Contactless Smart Cards incorporating MF3ICD40 or compatible Chip FOR USE IN Delhi Metro AFC System.

That against the Delhi Metro Tender No. DMRC/CO/ST/PUR/M&P/02.11.468 which was opened on <<date>>, M/s-----submitted their Bid No -----dated----- offered the contactedless DESfire Smart Cards 4 KB as tendered.

That the said M/s -----has submitted as per the tender conditions, a letter dated-----from the Chip OEM Manufacturers M/s ----- confirming full support for the supply of the modules for the Delhi Metro Project to the said firm, and as per the delivery requirement of Delhi Metro.

That as per the tender conditions -----, the Chip OEM and the said vendor M/s----- hereby confirm and agree to supply quality and functional modules of MF3ICD40 or compatible Chip as suitable to work in Delhi Metro AFC system.

That M/s----- confirm and agree to manufacture and supply quality cards using the modules being supplied by -----, Chip OEM directly or through their India Distributors.

That both Chip OEM M/s ----- and the vendor M/s-----jointly confirm and guarantee the functionality of the module/card for the entire guarantee/warranty period as specified in tender Document from the date of supply.

That the Chip OEM M/s ----- will supply quality modules and ensure functionality of the modules supplied to the card vendor as per the specifications stated in the data sheet of MF31ICD40 or compatible.

That Chip OEM M/s----- will guarantee the module for the warranty period as specified in the tender Document. M/s-----will manufacture quality cards as per ISO 14443-A standards and Arsenal Certification using the quality modules supplied by Chip OEM M/S ----- with copper wire embedded antennae. The cards will be tested at various stages of manufacture before supply, to ensure all the cards shipped to Delhi Metro are only functional cards. The guarantee, as specified in the tender Document will not cover breakage of cards, physical damage, bends, cuts, holes on the cards, intentional peel-off.

It shall be the joint responsibility of Chip OEM & Card Vendor to analyze the defective cards and replace the cards within the warranty period to DMRC for fault attributable other than those mentioned above.

IN AGREEMENT WHEREOF, THE BELOW PARTIES HJERETO HAVE SET THEIR HANDS AND SEAL TO THESE PRESENTS ON THE DAY, MONTH AND YEAR FIRST ABOVE WRITTEN IN THE PRESENCE OF THE FOLLOWING WITNESSES.

Delhi Metro Rail Corporation Ltd

CHIP OEM M/s-----

M/s-----

Authorized signatory

Authorized Signatory

Authorized Signatory